

ICS 31.200
CCS L 55



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 43931-2024

**General specification for microwave integrated circuit chip for
aerospace**

宇航用微波集成电路芯片通用规范

Issued on: June 29, 2024

Implemented on: October 1, 2024

**Issued by: State Administration for Market Regulation;
Standardization Administration of the PRC**

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Foreword

This document is in accordance with the provisions of GB/T 1.1-2020 "Guidelines for standardization work Part 1: Structure and drafting rules for standardization documents" Drafting.

Please note that some of the contents of this document may involve patents. The issuing organization of this document does not assume the responsibility for identifying patents.

This document was proposed and coordinated by the National Technical Committee for Standardization of Aerospace Technology and Its Applications (SAC/TC425).

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General specification for microwave integrated circuit chips for aerospace use

1 Scope

This document specifies the technical requirements, quality assurance regulations and delivery preparation for microwave integrated circuit chips for aerospace use.

This document applies to the design, production and product quality assurance of aerospace microwave integrated circuit chips (hereinafter referred to as "chips").

2 Normative references

GB/T 2828.1-2012

GB/T 2900

GB/T 4937.17-2018

GB/T 4937.18-2018

GB/T 4937.19-2018

GB/T 4937.22-2018

GB/T 4937.23-2023

GB/T 4937.26-2023

GB/T 19403.1-2003

GB/T 35010.1-2018

IEC 60749

IEC 60749

IEC 60749

3.1 Terms and Definitions

The terms and definitions defined in GB/T 2900 (all parts) and GB/T 35010.1-2018 apply to this document.

3.2 Abbreviations

The following abbreviations apply to this document. DRC. Design Rule Check